	- Utech
Name :	
Roll No.:	To Democry Samuely and Explana
Invigilator's Signature :	

CS/B.Tech (ECE-NEW)/SEM-6/EC-604/2011 2011 VLSI CIRCUITS AND SYSTEM

Time Allotted: 3 Hours Full Marks: 70

The figures in the margin indicate full marks.

Candidates are required to give their answers in their own words as far as practicable.

GROUP - A

(Multiple Choice Type Questions)

- 1. Choose the correct alternatives for any ten of the following: $10 \times 1 = 10$
 - i) What is the intermediate step between circuit design and fabrication in VLSI?
 - a) logic design
 - b) physical design
 - c) functional representation
 - d) system specification.
 - ii) Channel less gate array is a sub type of
 - a) standard gate ASIC b) configurable ASIC
 - c) full custom ASIC d) gate array ASIC.

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iii) Always interconnection will be neighbouring modules means



- a) locality
- b) regularity
- c) modularity
- d) synthesis.
- iv) Why band bending in MOSFET structure occurs?
 - a) difference of work function
 - b) natural phenomena
 - c) due to application of electric field
 - d) none of these.
- v) An ideal constant current source gives a current of 200 mA, for a load resistance of 500 Ω when it is short circuited, the current is
 - a) 40 mA

- b) 50 mA
- c) 100 mA
- d) 200 mA.
- vi) A MOS diode cannot be used as a component of
 - a) current mirror
- b) rectifier circuit
- c) level translator
- d) current sink.
- vii) In a CMOS Inverter circuit which of the following will act as driver?
 - a) depletion type PMOS
 - b) depletion type NMOS
 - c) enhancement type PMOS
 - d) enhancement type NMOS.

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viii) To implement the Boolean function $F = (A + B) \cdot (C + D)$ using Pseudo NMOS logic design number of transistor required is

a) 3

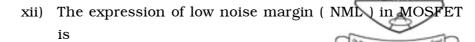
b) 4

c) 5

- d) 6.
- ix) The model parameter LAMDA (λ) in a MOS structure stands for
 - a) flicker noise coefficient
 - b) transit time
 - c) channel length modulation
 - d) transconductance.
- x) Frequency compensation for an OP-AMP can be achieved by
 - a) increase gain
 - b) adding zero
 - c) minimize overall phase shift
 - d) none of these.
- xi) The expression for body effect coefficient in MOSFET is
 - a) (2qNA ε si) 1/2 / Cox.
 - b) (2qNA ϵ si) / Cox.
 - c) (4qNA ϵ si) 1/2 / Cox.
 - d) (4qNA ϵ si) / Cox.

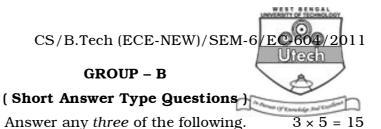
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- a) $V_{IL} V_{OL}$
- b) V_{OL} V_{IL}
- c) $V_{OH} V_{IH}$
- d) $V_{IH} V_{OH}$.
- xiii) For $0.25 \mu m$ process what is the value of λ ?
 - a) 0.5 μm
- b) 0·125 μm
- c) 0.75 μm
- d) 1 μm.
- xiv) Soft node leakage problems of CMOS NORA structure can be reduced using
 - a) TSPC logic
 - b) Zipper CMOS logic
 - c) NM logic
 - d) Cascaded domino logic.
- xv) Which domain is not included in three domains of Y chart?
 - a) system specification
- b) structural
- c) geometrical layout
- d) beavioural.
- xvi) Latch up occurs for CMOS as
 - a) CMOS invariably picks up stray signal
 - b) unavoidable existence of npn, pnp transistors embedded in CMOS
 - c) absence of parasitic effect
 - d) CMOS has low power dissipation.

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- 2. a) Draw the flow chart of VLSI design flow and explain.
 - b) What are the different design rules ? Discuss each in brief. 3+2
- Explain how a combination of switches and capacitors can be used to emulate a resistor.
- 4. What are the advantages of dynamic CMOS logic having precharge and evaluate phase?
- 5. a) What do you mean by CMOS transmission Gate (TG)?
 - b) Design the following circuits using transmission gates
 - i) Half adder
 - ii) D flip-flop. 2 + 3
- 6. Why is reference voltage required in IC ? What are the criteria for a good reference voltage source in a VLSI circuit ? 2+3

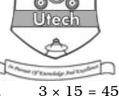
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GROUP - C

(Long Answer Type Questions)

Answer any three of the following.



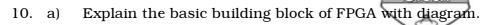
- 7. a) What do you mean by rise time (t_r) , fall time (t_f) and delay time (t_d) ?
 - b) Prove that W_p (channel width of P-MOS) = $2.5~W_n$ (Channel width of N-MOS).
 - c) Explain Dynamic CMOS Logic and Domino CMOS Logic with suitable diagram. (1+1+1)+4+(4+4)
- 8. a) Write the basis steps of fabrication.
 - b) Describe the *n*-well fabrication process with a suitable diagram.
 - c) Draw the schematic diagram of $Y = (A + B) \cdot (C + D)$

4 + 8 + 3

- 9. a) What is static and dynamic power dissipation in a MOS circuit?
 - b) What is routing capacitance in a MOS? Deduce switching characteristics rise time, fall time and delay time of an inverter circuit. (4+4)+(3+4)

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- b) What is PLA?
- c) Implement $f_1(a, b, c) = \Sigma m(3, 5, 6, 7)$ and $f_2(a, b, c) = \Sigma m(0, 2, 4)$ using PLA.
- d) Explain the design flow of an ASIC. 6 + 1 + 3 + 5
- 11. Write short notes on any *two* of the following :
 - a) FPGA
 - b) Design rule checker (DRC)
 - c) Phase locked loop
 - d) Comparator
 - e) ASIC

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